

Article 2 Terms and symbols used in these Standards are defined as follows:

1. “Semiconductor manufacturing industry” mean operators engaging in integrated circuit wafer manufacturing, wafer packaging, epitaxy, photomask manufacturing, lead frame manufacturing, etc.
2. “Integrated circuit wafer fabrication” means the operations to produce wafers of various specifications intended for various uses, including physical vapor deposition, chemical vapor deposition, photoresistance, photolithography, etching, diffusion, ion implantation, oxidation, heat treatment and other processes.
3. “Integrated circuit wafer package” means the operations to produce semiconductor products from completed wafers intended for various uses, including cutting into dice, followed by welding, electroplating, organic solvent washing, acid washing and other processes.
4. “Photoresist” means the acid-resistant photosensitizer required during the selective etching process in the manufacture of integrated circuit wafers.
5. “Photoresist process” means the process in which wafers undergo photoresist coating, exposure and development in order to produce various types of circuits on wafers.

6. “Volatile Organic Compounds (VOCs)” mean the general designation for air pollutants with an initial boiling point measured below 250 degrees Celsius at one bar pressure, which, however, does not include methane, carbon monoxide, carbon dioxide, carbon disulfide, carbonic acid, carbonate, ammonium carbonate, cyanide, thiocyanide and other compounds.
7. “Closed gathering system” means a system that can trap air pollutants emitted or released from processes, pollution sources or equipment components, and keep them from directly contacting the atmosphere. Such system includes gas gathering equipment, pipelines and connecting devices.
8. “Discharge reduction rate” means the emission reduction percentage of air pollutants treated by pollution prevention and control equipment, which is calculated based on the concentration and emission volume of exhaust gases at the front end and back end of the pollution prevention and control equipment through synchronous monitoring or detection. The calculation formula is as follows:

$$R = \frac{E - E_0}{E} \times 100\%$$

R: Discharge reduction rate.

E: Unit hourly discharge volume of air pollutants before they enter the pollution prevention and control equipment via the closed gas gathering system; the unit is kg/hr.

E₀: Unit hourly discharge volume of air pollutants directly discharged into the atmosphere through the pollution prevention and control equipment; The unit is kg/hr.

9. Existing process means the semiconductor manufacturing process that has been completed, is under construction, has its

project bidding process completed, or has the contract for the construction of the project executed without the bidding process prior to the promulgation of these Standards.

10. “Newly established process” means the semiconductor process established on the date of promulgation and implementation of these Standards, and the existing semiconductor process complies with the modification conditions stipulated in the Stationary Pollution Source Installation, Operating and Fuel Use Permit Management Regulations Amended Clauses.
11. “Annual consumption of volatile organic compounds (VOCs)” means the product of the approved maximum design quantity of all raw materials (supplies) set forth in all fixed pollution source operating permits times the percentage of VOCs in such raw materials (supplies) for any object listed in Paragraph 1 in a single public or private premises; the unit is ton/year.
12. “Total plant discharge quantity” means the sum of all individual air pollutants discharged from all discharge pipes within the peripheral boundaries of a single plant per hour; the unit is kg/hr.
13. “Effective quarterly monitoring rate” means (hours of pollution source operations per quarter - hours of flowmeter or concentration monitor failure during pollution source operations per quarter)/hours of pollution source operations per quarter.
14. Flowmeter means any facility that can directly or indirectly measure the volume flow rate of exhaust gas emissions.